SECTOR TECHNOLOGIES

Products brochure 2016.1

Electrical Test

teseda V550 — Tester for laboratories
- DFT
- Scan chain debug
- Curve Tracer, etc.

Mu-TEST M-5S, M-21S — Multi-purpose ATE Tester
- High Performances

Up to 1344 channels, High speed 1.6 Gbit, APG for DDR2/3 test, mixed signal channels, VI channels

Focused Test, Inc. FTI-1000 — Power Discrete, IGBT, GaN-SiC, Analog IC Tester

Package/ Board FA

FEI ELITE — Real Time Lock-in Thermography
Systems | Packages | Silicon
- Power Modules
- 3D localization
- Transient analysis
- Thermal mapping
- Improved sensitivity of the new camera (3X)
- Resistive defects localization

ZEISS xradia VersaXRM 410, 510, 520 — X-Ray Microscope
Packages are large — Defects are small
- 3D True resolution
- 0.7 µm resolution at distance
- Best absorption and phase contrast
- 300 mm wafer capability
- 4D and in-situ analysis

TeraView EOTPR — TeraHertz TDR
- Detect opens, shorts
- 5 µm spatial resolution

Insight k.k. IS-250, IS-350 — Scanning Acoustic Microscope
- Wide application range
- 0.1 µm spatial resolution
- High speed technology
- Compact size

Sample Prep

LightRAY Decap 10 — Fiber Laser Ablation
20 W pulsed fiber laser
- For fast and reproducible package pre-opening

Nisene JetEtch Pro, CuProtect, Total Protect — Acid Decapsulation
- Protect copper from corrosion
- Electrolytic chamber
- Temperature control

Nisene PlasmaEtch — Plasma Decapsulation
- Acid-free, low temperature
- Focused/ isotropic etching
- Latest solution for silver wires and complex packages

varioscale VarioMill — Precision Milling
- For ultimate silicon backside thinning

varioscale VarioMetric — Metrology
- High precision laser-based thickness measurements

Optics, Silicon FA

SEIWA OPTICAL — NIR Imaging
- To improve sensitivity of your EMMI tools
- To optimize laser transmission
- For generic use (Microscopes, NUV/ IR lenses)

Lens	20x	50x	100x
NA	0.6	0.7	0.75
WD	10 mm	10 mm	10 mm
Transmission	>70% (1µm-2µm)	>70% (1µm-2µm)	>80% (1µm-1.6µm)

Silicon Die FA

FEI — EFA
✓ Standard application (EMMI, OBIRCh)
✓ New Technologies (LVx, High NA SIL)

Meridian IV, Waferscan WS-DP, Meridian M

The most comprehensive platform for Electrical Failure Analysis (EFA)
- Emission Microscopy, OBIRCh, Laser Voltage Imaging & Probing
- Down to 14nm technology node, High NA SIL imaging
- Low noise, high sensitivity, extended-wavelength "next generation" camera (DBx)
- Waferscan— Wafer level FA due to semi-automated wafer prober

FEI — Thermal Emission
✓ Sensitivity & Resolution

ELITE

Lock-in thermography system for resistive defects localization
- SIL lenses
- High-Doped Silicon Lens
- Thermal mapping
- New high speed camera and SW

FEI — NanoProbing
✓ Efficiency toward electrical analysis

nProber II

Transistor probing on sub-14 nm nodes devices
- up to 8 encoded nanoprobes, HR SEM imaging
- Electron Beam Induced/Absorbed Current (EBIC/EBAC)

Hyperion
- up to 8 encoded nanoprobes, HR AFM imaging
- PicoCurrent™, Scanning Capacitance modes
- Dynamic characterization capability (Pulsed IV)

FEI — Dynamic FA
✓ Timing & Functional Analysis

Meridian V

Proven on 14 nm technology node
- Optimized dynamic LSM platform
- LVI, LVP, OBIRCh, Soft Defect Localization
- Design Debug
- Highest performance High NA SIL and imaging

FEI — Circuit Edit
✓ Front-side / Back-side FIB

OptiFIB Taipan

Down to 10 nm technology
- Broadest range of chemistries
- New coaxial ion-photon column
- Excellent navigation and ion beam placement

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Providing Effective Solutions...